



Title of Change:	Final PCN for the change of mold compound in ATPAK.							
Proposed first ship date:	3 November 2016 <i>or earlier upon customer approval</i>							
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasunari.Noguchi@onsemi.com>							
Samples:	Contact your local ON Semiconductor Sales Office							
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume @onsemi.com>.							
Type of notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.</p>							
Change Part Identification:	Affected products will be identified with date code.							
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____							
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Shenzhen, China <input type="checkbox"/> External Foundry/Subcon site(s)							
Description and Purpose:	<p>This is a Final Process Change Notification to announce the change of mold compound. The details goes as follows:</p> <p>1) The changing mold compound from GE-1030 to EME-G700.</p> <table border="1" style="width: 100%; text-align: center;"> <thead> <tr style="background-color: #92d050;"> <th></th> <th>Before change</th> <th>After change</th> </tr> </thead> <tbody> <tr> <td>Mold compound</td> <td>GE-1030</td> <td>EME-G700</td> </tr> </tbody> </table>			Before change	After change	Mold compound	GE-1030	EME-G700
	Before change	After change						
Mold compound	GE-1030	EME-G700						



Reliability Data Summary:

QV DEVICE NAME ATP304-TL-H

PACKAGE: ATPAK / DPAK (Single Gauge)

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
AC	JSTD020 JESD-A102	Tj=121°C, RH=100%, Pressure=15psig	96 hrs	0/231

PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ATP304-TL-H	ATP304-TL-H